



Material Content Data Sheet



Halogen-Free

Sales Product Name	IPTC014N08NM5	Issued	23. June 2021
MA#	MA005447495		
Package	PG-HDSOP-16-2	Weight*	854.62 mg

Construction Element	Material Group	Substances	CAS# if applicable	Weight [mg]	Average Mass [%]	Sum [%]	Average Mass [ppm]	Sum [ppm]
chip	inorganic material	silicon	7440-21-3	6.440	0.75	0.75	7535	7535
leadframe	inorganic material	phosphorus	7723-14-0	0.143	0.02		168	
	non noble metal	iron	7439-89-6	0.477	0.06		559	
	non noble metal	copper	7440-50-8	476.748	55.78	55.86	557847	558574
wire	non noble metal	aluminium	7429-90-5	20.842	2.44	2.44	24387	24387
encapsulation	inorganic material	zinc oxide	1314-13-2	3.238	0.38		3789	
	miscellaneous	miscellaneous	-	12.953	1.52		15156	
	plastics	epoxy resin	-	48.572	5.68		56835	
	inorganic material	silicon dioxide	60676-86-0	259.053	30.31	37.89	303120	378900
lead finish	non noble metal	tin	7440-31-5	6.684	0.78	0.78	7821	7821
plating	inorganic material	phosphorus	7723-14-0	0.013			15	
	non noble metal	nickel	7440-02-0	5.316	0.62	0.62	6220	6235
solder	non noble metal	tin	7440-31-5	0.107	0.01		125	
	noble metal	silver	7440-22-4	0.133	0.02		156	
	non noble metal	lead	7439-92-1	5.093	0.60	0.63	5959	6240
heatspreader	inorganic material	phosphorus	7723-14-0	0.003			3	
	non noble metal	iron	7439-89-6	0.009			10	
	non noble metal	copper	7440-50-8	8.798	1.03	1.03	10295	10308
*deviation	< 10%	Sum in total:				100.00		1000000

Important Remarks:

1. Infineon Technologies AG provides full material declaration based on information provided by third parties and has taken and continues to take reasonable steps to provide representative and accurate information.
2. Infineon Technologies AG and Infineon Technologies AG suppliers consider certain information to be proprietary, and thus CAS numbers and other limited information may not be available for release.
3. All statements are based on our present knowledge, are provided 'as is' and may be subject to change at any time due to technical requirements and development without notification.

This product is in compliance with EU Directive 2015/863/EU amending Annex II to EU Directive 2011/65/EU (RoHS) and contains Pb according RoHS exemption 7a, Lead in high melting temperature type solders.

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